



**POLYRACK
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Press release

POLYRACK at the MtoM & Objets Connectés – Embedded Systems:
Hall 5.3, Booth F26

Case and system applications for individual requirements

Straubenhardt, February 12th, 2018 – The POLYRACK TECH-GROUP will be presenting at the MtoM & Objets Connectés – Embedded Systems (21.-22. March 2018 in Paris) in hall 5.3, booth F26 their wide range of case and system solutions for embedded systems. Customer-specific system applications from various branches and application fields including integration of electronics and a range of HMI and MMI applications will be displayed.

For the embedded market, particularly for industrial environments, POLYRACK presents its **PanelPC 2-series**. These Panel-PC-solutions satisfy the protection class IP54 and are available in sizes from 10.1“ to 21.5“ as well as in different materials such as milled aluminium or sheet metal bending solutions. Resistive single-touch or multi-touch capable touchscreens (PCAP) in different glass thicknesses are options for the user interface. Customer specific printing and anti-fingerprint coating are available on request. In order to use the advantages of different materials, other technologies are available for customers to realize individual requirements in materials, such as plastics and castings – also in a material combination mix.

Small Form Factor with EmbedTEC: The aluminium table top case is the elegant design for small form factors such as embedded NUC (eNUC), pico-ITX (pITX, 2.5“), SMARC, QSeven and SBCs as well as the Raspberry Pi. It comes with a changeable front I/OShield as well as a massive aluminium cover for the heat dissipation. The cover

might as well be replaced by a heat sink for improved performance. Alternatively, perforated side panels or small fans can add to the cooling performance on top. POLYRACK also offers various adaptations and mounting options for applications in the fields of automatization and IoT.

The heavy-duty system platform **Rugged MIL ½ Short ATR Chassis** has been especially developed for rough environments. Available as dip-brazed aluminium or as alternative sheet metal bending solution according to ARINC 404A, it protects electronic components against mechanical, climatic, chemical and electrical influences. The platform is passively cooled and satisfies the specification standards MIL- 810 and ARINC 404A. POLYRACK also offers applications with active and hybrid (passive and active) cooling as well as liquid cooling. The ATR Chassis can be configured as a complete system with Backplanes according to the standards VITA- (VMEbus, VME64x, VPX, OpenVPX) or PICMG (CPCI, CPCI Serial, CPCI Plus I/O), power supply units and I/O-connection boards.

POLYRACK will be presenting additional highlights such as:

- **SmarTEC** for high quality systems such as passive cooled Mini-PCs
- **EmbedTEC** for Embedded Computing and HMI-applications
- **Backplanes** for the high-speed domain based on VPX and CompactPCI Serial standards

All POLYRACK solutions are characterized by suitable interaction of mechanics, plastics, electronics and surface finish – adapted to the target market.

Pictures:



Picture 1: The PanelPC 2-Series is available in different display sizes and user interfaces.



Picture 2: EmbedTEC for Small Form Factor (SFF)



Picture 3: Ideal for rough environments: The POLYRACK Rugged MIL ½ ATR Chassis.



Picture 4: Rugged Air-Cooled 3/4-ATR VME System

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About POLYRACK TECH-GROUP (www.polyrack.com)

The POLYRACK TECH-GROUP develops and manufactures high quality standard cases and customer-specific enclosure solutions. Thanks to a broad range of technologies in the mechanical manufacturing, systems engineering / electronics, plastics and surface finishing, POLYRACK offers electronic packaging for every need. The service offering extends from consulting in the conception phase, development, manufacturing and assembly right through to logistic solutions and sourcing services. The company group comprises the POLYRACK Electronic-Aufbausysteme GmbH (Electronic Packaging and Systems Technology), RAPP Kunststofftechnik GmbH (Plastics Technology), RAPP Oberflächenbearbeitung GmbH (Surface Treatment) and subsidiaries in Switzerland, Belgium, America and China. The owner-managed company has 410 employees worldwide and achieved a turnover of 65 million euros in total in the group in fiscal year 2017.

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